

MULTIPLIER - DIVIDER

FEATURES

- DIFFERENTIAL INPUTS
- LASER-TRIMMED
- GUARANTEED ACCURACY 0.5% and 1%
- SELF-CONTAINED
 No additional parts required
- LOW NOISE 120Vrms, 10Hz – 10kHz
- DIP PACKAGE

APPLICATIONS

- MULTIPLICATION
- DIVISION
- SQUARING
- SQUARE ROOTING
- ADAPTIVE CONTROL
- ALGEBRAIC COMPUTATION
- POWER COMPUTATION

DESCRIPTION

The 4214 family of multipliers are low-cost integrated circuit multiplier/dividers designed for general purpose usage. In addition to four-quadrant multiplication, they also perform division and square rooting of analog signals. They do not require use of additional amplifiers to perfrom these functions. The 4214 is laser-trimmed prior to final packaging and is guaranteed to its rated accuracy with no external components—a distinct advantage from standpoints of cost and reliability.

The 4214 contains its own zener-regulated references and, as a result, is much less sensitive to supply voltage variation than were earlier IC multipliers. The multipliers' output noise is only 120Vrms in a 10Hz to 10kHz bandwidth.

The unit is packaged in a 14-pin ceramic DIP package and available in both -25°C to +85°C and -55°C to +125°C specification temperature ranges.

SPECIFICATIONS

ELECTRICAL

Typical performance at +25°C with rated power supplies unless otherwise noted.

MODEL	4214AP/RM	4214BP/SM		
OUTPUT FUNCTION	(X ₁ - X ₂) ($\frac{(X_1 - X_2) (Y_1 - Y_2)}{10} + Z_2$		
TOTAL ERROR(1)				
Without Trimming	i% max	0.5% max		
Error vs Temperature (-25°C to +85°C), (AP and BP) (-55°C to +125°C), (RM and SM)		0.008%/°C typ., 0.02%/°C max 0.025%/°C typ., 0.05% °C max		
Error vs Supply	0.03	0.05%/%		
INDIVIDUAL ERRORS				
Output Offset	10mV typ	7mV typ		
onput ontal	50mV max			
vs Temperature	0.7mV/°C typ			
	2mV/°C max			
vs Supply		nV/%		
Scale Factor Error		2%		
vs Temperature		08% °C		
vs Supply		%/%		
Nonlinearity				
$X(X = 20V p-p, Y = \pm 10VDC)$	±0.	08%		
$Y(Y = 20V p - p, X = \pm 10VDC)$	±0.	01%		
Feedthrough at 50 Hz	1			
X = 20V p-p, Y = 0	30mV p-p			
Y = 20V p-p, X = 0	6m\	(p-p		
vs Temperature	0.1m	V p-p °C		
vs Supply	0.15mV p-p. %			
AC PERFORMANCE	1			
Small Signal ±3dB Flatness		kHz		
Small Signal ±1% Flatness	90 kHz 7.5 kHz			
Small Signal ±1% Vector Error (0.57" Phase Shift)	330 kHz			
Full Power Bandwidth	23V : µ5			
Siew Rate	1.7µs			
Settling Time to 1% (20V step)	+	- μ-		
OUTPUT NOISE (X = Y = 0)				
10 Hz to 10 kHz		120µV rms 700µV rms		
10 Hz to 10 MHz	700	V rms		
INPUT CHARACTERISTICS				
Input Voltage Range	1			
Rated Operation, min.		±10V		
Absolute max	1	±V,		
Input Impedance, X, Y, Z ⁽²⁾		10 MΩ		
Input Bias Current, X, Y, Z	1	.4μA		
OUTPUT CHARACTERISTICS				
Rated Output	*10V at	±5mA min		
Output Impedance		1.50		
Compos Ampedance				
POWER SUPPLY REQUIREMENTS	1			
Rated Voltage	1 :	15V		
	±8.5VDC to ±20VDC			
Operating Range	±5.5mA			
Operating Range Quiescent Current				
Quiescent Current				
Quiescent Current TEMPERATURE RANGE AP and BP		to +85°C		
Quiescent Current TEMPERATURE RANGE Rated Performance (specification) RM and SM	-55°C	to +125°C		
Quiescent Current TEMPERATURE RANGE AP and BP	-55°C			

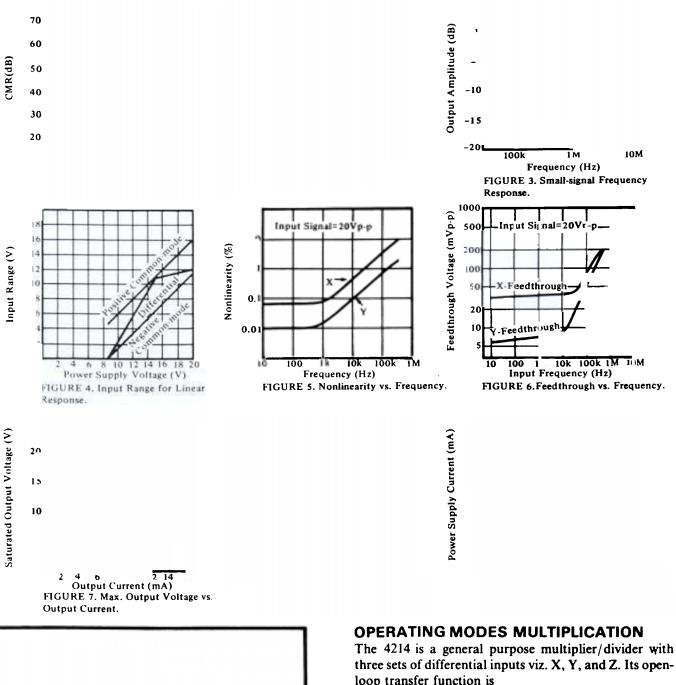
MECHANICAL

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CONNECTION DIAGRAM

- 1. Total error is the maximum allowed value of the sum of the individual errors.
- 2. Z_2 input impedance is 10 M Ω typ with Pin 11 open circuit. If Pin 11 is grounded or used for optional offset adjustment the Z_2 input impedance may become as low as 25k Ω .

TYPICAL PERFORMANCE CURVES



three sets of differential inputs viz. X, Y, and Z. Its openloop transfer function is

$$e_0 = A \left[\frac{(X_1 - X_2)(Y_1 - Y_2)}{10} - (Z_1 - Z_2) \right]$$

where, A is the open-loop gain of the internal output amplifier (see the simplified equivalent circuit, Figure 10). Due to very high gain $(A \rightarrow \infty)$ of the output amplifier the feedback from the output to any of the inputs will establish the relationship

$$Z_1 - Z_2 = (X_1 - X_2) (Y_1 - Y_2) / 10$$

Taking output at Z₁ the multiplication mode transfer function is obtained and is expressed as

$$e_0 = \frac{(X_1 - X_2)(Y_1 - Y_2)}{10} + Z_2.$$

This connection of 4214 is shown on page 2.

DIVISION

The 4214 may be used as a two quadrant divider, without the need for an external op amp. Note that the maximum output error in the divide mode is given approximately by,

Divider error
$$\simeq \frac{10 \in m}{X_1 - X_2}$$
, where $\in m$ is

the total error specified for the multiply mode. The divider error, as shown above, becomes excessively large for small values of $(X_1 - X_2)$. A 10:1 denominator range is usually the practical limit. This is true for all such units, where a multiplier is used in voltage feedback mode to generate "divide" function.

If more accurate division is required over wide range of denominator voltages, the Burr-Brown model 4291 is recommended (0.25% max error over 100:1 range).

For optimum performance, the Z offset should be nulled by letting the input be zero and adjusting R_1 for zero output. This offset adjustment will improve the divider error to about $3 \in_{\mathbf{M}}$ for $(X_1 - X_2)$ much less than 10V.

FIGURE 11. Divide Mode Connections—4214.

SQUARE ROOT

By applying feedback from the output to both the X and Y inputs, the square root function can be obtained. The errors in the square root mode become large for small values of Z input. The actual output is approximately

Square root output $e_0 = \sqrt{10(Z_1 - Z_2) + 10} \in m$ where $\in m$ is the total error for the multiply mode.

Burr-Brown's multifunction converter model 4302 is recommended for applications requiring more accuracy over wider dynamic range.

The output offset should be nulled for optimum performance by allowing the input to be its smallest expected value and adjusting R_1 for the proper output voltage.

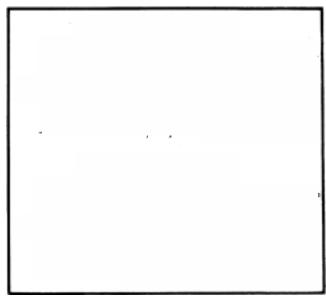


FIGURE 12. Square Root Mode Connections—4214.

SINE FUNCTION GENERATOR

Two 4214's can be connected with implicit feedback as shown in Figure 13 to implement the following sine function approximation.

$$e_0 = \frac{1.5715 e_1 - 0.004317 e_1^3}{1 + 0.001398 e_1^2} = 10 \sin 9 e_1$$

The theory and procedures for developing virtually any function generator or linearization circuit can be found in the new Burr-Brown/McGraw Hill book "FUNCTION CIRCUIT - Design and Applications."

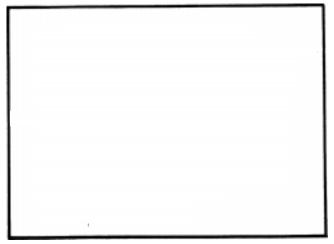


FIGURE 13. Sine Function Connections—4214.

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PACKAGE OPTION ADDENDUM

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
4214AP	NRND	CDIP SB	JD	14	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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